



*Request OEM Report*

*Notes:*

*Equipment impacted by a CDA event that allowed excessive moisture to enter the tool through the CDA supply line.*

*Equipment considered as parts sale only due to this.*

*CDA Lines showed water droplets at virtually all major and sensitive units.*

*Started purging at CDA source to stepper, and level of contamination was beyond initial thoughts.*

*CDA lines went from showing water droplets, to fully saturated.*

*After discovering water as more than just droplets in CDA lines & large amounts accumulated in low areas and near some fittings, decision to disassemble regulator & gauge panel.*

*CDA purging of individual lines went from sprays of water, to water flows & streams of water shooting from the piping when pressure applied.*

*Moisture absorbent pads were positioned around the stepper to contain the large amounts of water.*

*These large accumulations of water were found at the: regulator panel, wafer stage and damper distribution box, & at the Ulens purging distribution box.*

*Water was also found in the piping at the top of the chamber above the HEPA filters*

*For the most critical area, Ulens purging. Large amounts of water were found in piping.*

*All 4 lines to the Ulens contained water.*

*Cannon has no field procedure to determine what has entered the Ulens, but must make the assumption that with water in the piping to the Ulens purge, water is likely inside the Ulens.*

*Stepper will be reassembled, as Canon feels no further need to look for contamination at the CDA cooling supplied for the exposure shutter, masking blade unit, and illuminator.*

*Date of audit: 9/30/20025*

*Model*

*FPA-3030i5+*

*Wafer Size (inches)*

*6*

*Install Type: TTW / Stand-Alone*

*Stand-Alone*

*OEM MFG Date*

*2020*

*Install Date*

*2020*

*Is System On-Line?*

*NO*

*Off-Line Date (if applicable)*

*6/28/2024*

*Can Produce Wafers As-Is ?*

*NO*

*CE Mark Certified ?*

*YES*

*Are any Manuals included ?*

*Partial*

*OEM Audit Available?*

*YES*

*3rd Party Audit Available ?*

*NO*

*Decontamination Report Exists?*

*YES*

*Any Field Modifications ?*

*NO*

*All Cables present ?*

*YES*

*Any Corrosion visible on modules ?*

*YES*

*Any Missing / Damaged Parts ?*

*YES*

*Shipping Brackets Included ?*

*YES*

*Wafer Handler*

*YES*

*Handler Type*

*SiC Handling*

*# of Cassette / FOUN Loaders*

*Cassette Stage*

*Robot Type*

*OEM*

*End-Effector Type*

*OEM*

*Pre-Aligner ?*

*YES*

*Mini-Environment*

*YES*

*Handler Options ?*

*SiC substrate*

*GEM / SECS ?*

*Yes*

*HSMS*

*Yes*

*Supporting Equipment*

*Std OEM items*

*CDA*

*N2*

*DIW*

*Chilled Water*

*Vacuum*

*Yes*

*Gas*

*NA*

*Power*

*200 3-phase 102A*